

AO9926

Dual N-Channel Enhancement Mode Field Effect Transistor

General Description

The AO9926 uses advanced trench technology to provide excellent $R_{\rm DS(ON)},$ low gate charge and operation with gate voltages as low as 1.8V while retaining a 12V $V_{\rm GS(MAX)}$ rating. This device is suitable for use as a uni-directional or bi-directional load switch.

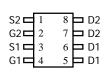
Features

 $V_{DS}(V) = 20V$ $I_{D} = 6 A (V_{GS} = 4.5V)$

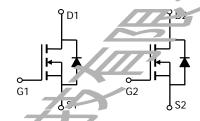
 $R_{DS(ON)}$ < 30m Ω (V_{GS} = 4.5V)

 $R_{DS(ON)}$ < 40m Ω (V_{GS} = 2.5V)

Pin Configuration



SOIC-8



Absolute Maximum Ratings T _A =25°C unless the with a noted								
Parameter	Syr.ibol	Maximum	Units					
Drain-Source Voltage	11 ns	20	V					
Gate-Source Voltage	V Co	±12	V					
Continuous Drain T _A =25°C		6						
Current ^A T _A =70°C	I_D	5	Α					
Pulsed Drain Current B	I _{DM}	24						
T ₂ -25 C	P _D	2	W					
Power Dissipation A T. = 70°C		1.3						
Junction and Storage remperature Range	T_J , T_{STG}	-55 to 150	°C					

Thermal Characteristics									
Parameter		Symbol	Тур	Max	Units				
Maximum Junction-to-Ambient A	t ≤ 10s	$R_{\theta JA}$	48	62.5	°C/W				
Maximum Junction-to-Ambient ^A	Steady-State	K _θ JA	74	110	°C/W				
Maximum Junction-to-Lead ^C	Steady-State	$R_{\theta JL}$	35	50	°C/W				

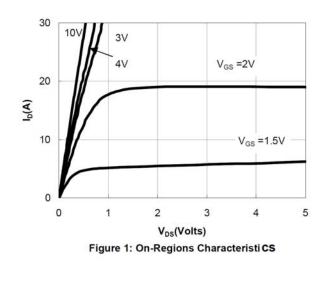


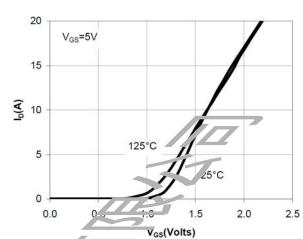
Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions		Min	Тур	Max	Units			
STATIC PARAMETERS										
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =250μA, V _{GS} =0V		20			V			
I _{DSS} Zero Gate Voltage Drain Current	V _{DS} =20V, V _{GS} =0V				1	μА				
	Zero Gate Voltage Brain Garrent		T _J =55°C			5	μΛ			
I_{GSS}	Gate-Body leakage current	V _{DS} =0V, V _{GS} =±12V				TUJ	nA			
BV_{GSO}	Gate-Source Breakdown Voltage	V_{DS} =0V, I_{G} =±250uA	±12			V				
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$ $I_{D}=250uA$		0.65	0.79	1	V			
$I_{D(ON)}$	On state drain current	V_{GS} =4.5V, V_{DS} =5V	4	30			Α			
R _{DS(ON)} Static Drain-Source On-Resistance	V _{GS} =10V, I _D =7.6A			18	23	mΩ				
	-	T _J =: <5 ⁻ L;		25	30	0 11122				
	V_{GS} =4.5V, I_D =6A			21	30	mΩ				
	V _{GS} =2.5V, I _D =5.2A			30	40	mΩ				
		V _{GS} =1.8V, I _D =2A			38	52	mΩ			
g FS	Forward Transconductance	V _{DS} =5V, I _D =6 <i>E</i> .			12		S			
V_{SD}	Diode Forward Voltage	I _S =1.7A,V _{GS} =0V			0.8	1	V			
Is	Maximum Body-Diode Continuous Current					1.7	Α			
DYNAMIC	CPARAMETERS									
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =8V, f=1MHz			522.3		pF			
Coss	Output Capacitance				98.48		pF			
C _{rss}	Reverse Transfer Capacitance				74.69		pF			
R_g	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1MHz			1.5		Ω			
SWITCHI	NG PARAMETERS	•								
Q_g	Total Gate Charge	V _{GS} =4.5V, V _{DS} =10V, I _D =6A			6.24	8.11	nC			
Q_{gs}	Gate Source Charge				1.64	2.13	nC			
Q_{gd}	Gate Drain Charge				1.34	1.74	nC			
t _{D(on)}	Turn-On Delaytime				10.4	20.8	ns			
t _r	Turn-On Ric a Tir le	V_{GS} =4.5V, V_{DS} =10V, R_L =10 Ω , R_{GEN} =6 Ω			4.4	8.8	ns			
t _{D(off)}	Turn-Off DelayTime				27.36	54.72	ns			
t _f	Tun-Off Fa Time				4.16	8.32	ns			
t _{rr}	Body Diode Reverse Recovery Time	I _F =7.6A, dI/dt=100A/μs			15.2		ns			
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =7.6A, dI/dt=100A/μs			6.3		nC			



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS





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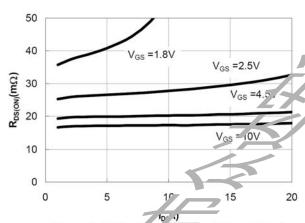


Figure 3: On-Resistance vs. Drain Current and Cate Voltage

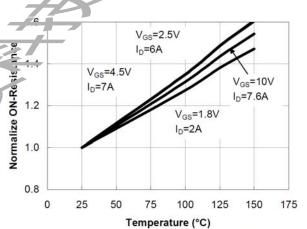


Figure 4: On-Resistance vs. Junction **Temperature**

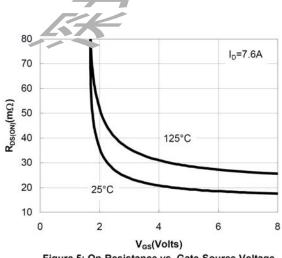
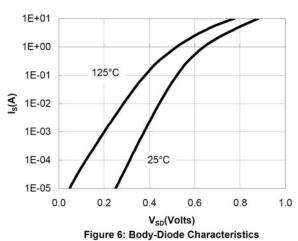
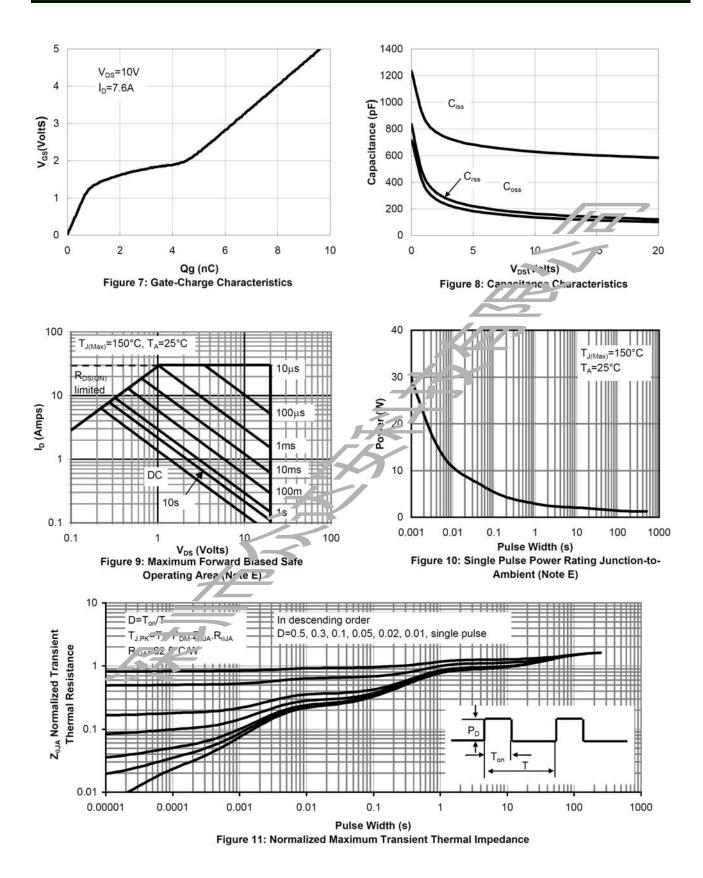


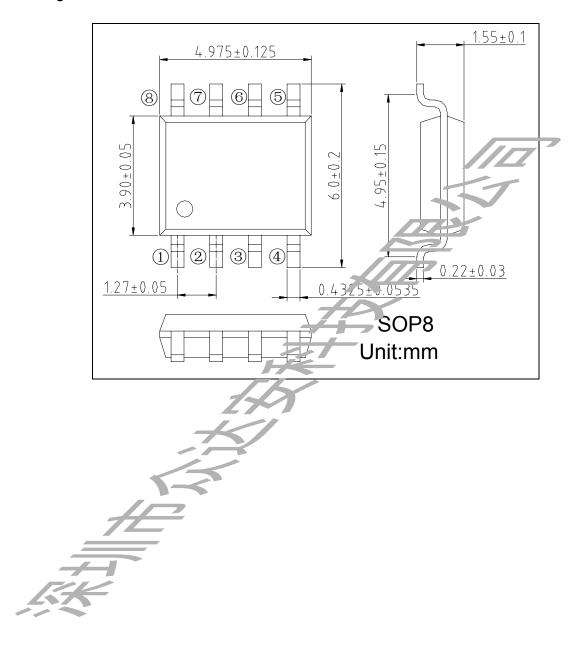
Figure 5: On-Resistance vs. Gate-Source Voltage







Package Information





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